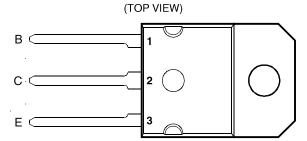


# BDV64, BDV64A, BDV64B, BDV64C PNP SILICON POWER DARLINGTONS

- Designed for Complementary Use with BDV65, BDV65A, BDV65B and BDV65C
- 125 W at 25°C Case Temperature
- 12 A Continuous Collector Current
- Minimum h<sub>FE</sub> of 1000 at 4 V, 5 A



**SOT-93 PACKAGE** 

Pin 2 is in electrical contact with the mounting base.

### absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT	
	BDV64		-60		
Collector-base voltage (I <sub>E</sub> = 0)	BDV64A	V.	-80	V	
	BDV64B	V <sub>CBO</sub>	-100		
	BDV64C		-120		
Collector-emitter voltage (I <sub>B</sub> = 0)	BDV64		-60		
	BDV64A	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	-80	V	
	BDV64B	V <sub>CEO</sub>	-100		
	BDV64C		-120		
Emitter-base voltage			-5	V	
Continuous collector current			-12	Α	
Peak collector current (see Note 1)			-15	Α	
Continuous base current			-0.5	Α	
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)		P <sub>tot</sub>	125	W	
Continuous device dissipation at (or below) 25°C free air temperature (see Note 3)		P <sub>tot</sub>	3.5	W	
Operating junction temperature range		Tj	-65 to +150	,C	
Storage temperature range			-65 to +150	,C	
Lead temperature 3.2 mm from case for 10 seconds			260	,C	

NOTES: 1. This value applies for  $t_p \leq 0.1$  ms, duty cycle  $\leq 10\%$ 

- 2. Derate linearly to 150°C case temperature at the rate of 0.56 W/°C.
- 3. Derate linearly to  $150^{\circ}$ C free air temperature at the rate of 28 mW/°C.

# BDV64, BDV64A, BDV64B, BDV64C PNP SILICON POWER DARLINGTONS

# electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER TEST CONDITIONS		MIN	TYP	MAX	UNIT				
V <sub>(BR)CEO</sub>	Collector-emitter breakdown voltage	I <sub>C</sub> = -30 mA	I <sub>B</sub> = 0	(see Note 4)	BDV64 BDV64A BDV64B BDV64C	-60 -80 -100 -120			V
I <sub>CEO</sub>	Collector-emitter cut-off current	$V_{CB} = -30 \text{ V}$ $V_{CB} = -40 \text{ V}$ $V_{CB} = -50 \text{ V}$ $V_{CB} = -60 \text{ V}$	$I_{B} = 0$ $I_{B} = 0$ $I_{B} = 0$ $I_{B} = 0$		BDV64 BDV64A BDV64B BDV64C			-2 -2 -2 -2	mA
Ісво	Collector cut-off current	$\begin{array}{c} V_{CB} = \; -60 \; V \\ V_{CB} = \; -80 \; V \\ V_{CB} = \; -100 \; V \\ V_{CB} = \; -120 \; V \\ V_{CB} = \; -30 \; V \\ V_{CB} = \; -40 \; V \\ V_{CB} = \; -50 \; V \\ V_{CB} = \; -60 \; V \\ \end{array}$	I <sub>E</sub> = 0 I <sub>E</sub> = 0	$T_{C} = 150^{\circ}C$ $T_{C} = 150^{\circ}C$ $T_{C} = 150^{\circ}C$ $T_{C} = 150^{\circ}C$	BDV64 BDV64A BDV64B BDV64C BDV64 BDV64A BDV64B BDV64C			-0.4 -0.4 -0.4 -0.4 -2 -2 -2	mA
I <sub>EBO</sub>	Emitter cut-off current	V <sub>EB</sub> = -5 V	$I_C = 0$					-5	mA
h <sub>FE</sub>	Forward current transfer ratio	V <sub>CE</sub> = -4 V	I <sub>C</sub> = -5 A	(see Notes 4 and	d 5)	1000			
V <sub>CE(sat)</sub>	Collector-emitter saturation voltage	I <sub>B</sub> = -20 mA	I <sub>C</sub> = -5 A	(see Notes 4 and	d 5)			-2	V
V <sub>BE</sub>	Base-emitter voltage	V <sub>CE</sub> = -4 V	I <sub>C</sub> = -5 A	(see Notes 4 and	d 5)			-2.5	V
V <sub>EC</sub>	Parallel diode forward voltage	I <sub>E</sub> = -10 A	I <sub>B</sub> = 0	(see Notes 4 and	d 5)			-3.5	V

#### thermal characteristics

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			1	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			35.7	°C/W

NOTES: 4. These parameters must be measured using pulse techniques, t<sub>p</sub> = 300 μs, duty cycle ≤ 2%.
 5. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

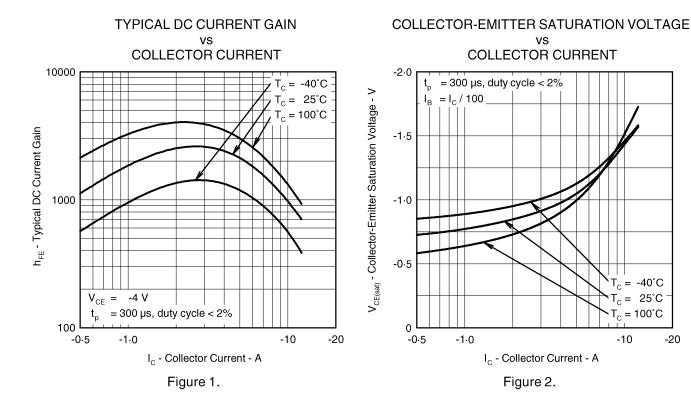
 $T_C = -40^{\circ}C$  $T_C = 25^{\circ}C$ 

 $T_C = 100^{\circ}C$ 

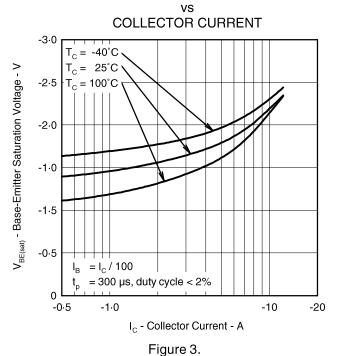
-20

-10

#### **TYPICAL CHARACTERISTICS**



## BASE-EMITTER SATURATION VOLTAGE



### THERMAL INFORMATION

# MAXIMUM POWER DISSIPATION

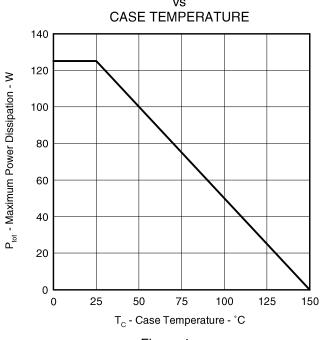


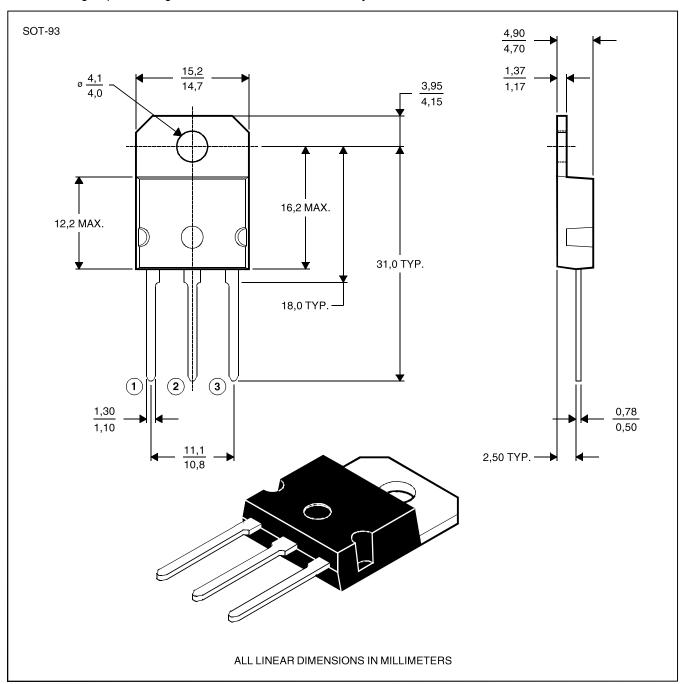
Figure 4.

#### **MECHANICAL DATA**

#### **SOT-93**

#### 3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.